

ECOFREC™ TF49 RED



No-Clean Red Tacky Flux For dispensing

FEATURES

ECOFREC™ TF49 RED is a tacky flux paste designed for soldering assembly, on site rework or after market repair of traditional components including surface mount devices.

ECOFREC™ TF49 RED is particularly efficient for leaded and lead free ball attach and BGA repair. Its red colour allows the automated optical inspection equipment to easily detect the flux during the process reducing false failures and optimizing the production output.

SPECIFICATIONS

Colour	red
Odour	very low
Solubility in water In alcohol	not soluble soluble
Classification according ANSI/J-STD-004	ROL0
Halogen content	no halogen
Density at 20°C	1
Viscosity (Pa.s at 20°C) <i>(Measured on BROOKFIELD RVT viscometer with Mobile F HELIPATH system, at 5 rpm)</i>	300 - 500

CHARACTERISTICS

ECOFREC™ TF49 RED is a high viscosity tacky flux made of a complex blending of rosins, activators and solvents.

PCBA cleaning is not required after soldering because **ECOFREC™ TF49 RED** residues are chemically inert and will not trigger corrosion.

FUNCTIONAL TESTS	RESULTS	PROCEDURES
Surface Insulation Resistance After 7 days 85°C / 85% RH-50V 25°C – 65% RH	pass > 10 ¹⁰ > 10 ¹²	ANSI/J-STD-004

PACKAGING

Syringe	10 g or 30 g
Plastic jar	100 g or 500 g
Cartridge	300 g

For an optimal preservation, store cartridges and syringes in vertical position, tip downwards.

STORAGE & SHELF LIFE

ECOFREC™ TF49 RED must be stored in a cool and ventilated area at room temperature. Shelf life is one year.

PROCESS PARAMETERS

ECOFREC™ TF49 RED can be applied by dispensing or screen/stencil printing.

The sticky properties of ECOFREC™ TF49 RED ensure that components are kept in position until the alloy is reflowed. A variety of heating methods may be used to produce the solder joint with ECOFREC™ TF49 RED. These include soldering irons, hot gas and hot bar devices, IR, convection oven, or vapour phase.

If printing, the tackiness can be improved by letting the boards stay at room temperature for 30-60 minutes before populating (or, as an alternative, heat the board to 50-60°C for a few minutes).

HSE

During soldering operations, vapours should be collected by an efficient exhaust system.
No issues when used as recommended.

Please refer to MSDS before use.

Although the conformity to ROHS 2002/95CE applies EQUIPMENT put on the market and not a component in particular, we warranty that this product contains less than 0.1% of mercury, lead, chromium VI, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE) and less than 0.01% for the cadmium, in accordance with the decision of The European Commission dated 18/08/2005, fixing the maximal concentration values.

This data is based on information that the manufacturer believe to be reliable and offered in good faith. In no event will INVENTEC be responsible for special, incidental and consequential damages. The user is responsible to the Administrative Authorities (regulations for the protection of the Environment) for the conformity of his installation.

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